PAC TECH
PACKAGING TECHNOLOGIES

Service
Equipment
Processes

Ultra-SB² 200/300

new

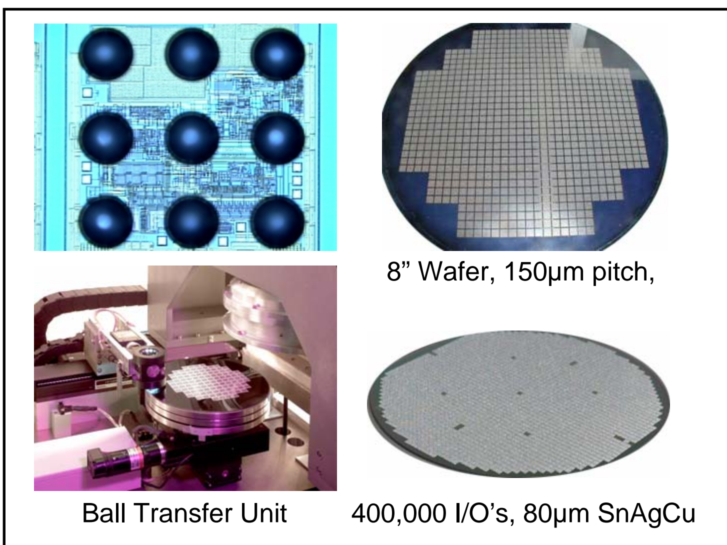
Micro Ball Bumping for
Flip Chip & Wafer Level CSP

Micro Solder Ball Placement on Wafer Level

Specifications:

- 60µm-760µm solder spheres
- Wafer sizes: 6", 8", 12"
- 120µm-1mm pad pitches
- Solder bump height coplanarity: < 10 µm @ 3 sigma
- flexible solder ball alloy compositions:
  all SnAgCu alloys, higher temperature alloys AuSn, PbSn
- High throughput
- Low tooling cost
- Volume production & prototyping capability
- 100% ball inspection and electronic wafer ink map update

Automatic Ultra-SB² 300



8" Wafer, 150µm pitch,

Ball Transfer Unit

400,000 I/O's, 80µm SnAgCu

Semiautomatic Ultra-SB² 200

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